



## Aaron C. Dilbeck Associate

### Attorney Bio

Aaron C. Dilbeck is an associate at Munck Wilson Mandala, practicing in the complex litigation/dispute resolution group. His practice is focused on intellectual property disputes and commercial litigation.

Aaron received his J.D. with honors from Southern Methodist University Dedman School of Law where he was executive editor of the SMU Science and Technology Law Review. Prior to law school, Aaron worked as a ceramics engineer providing research and development as well as quality assurance and control. Aaron is also the first listed inventor on a pending patent application.

He earned a bachelor of science degree in materials science and engineering from the University of Illinois at Urbana-Champaign. Aaron is a member of the Dallas Bar Association and licensed to practice in Texas.

### Practice Areas

Commercial Litigation  
Copyrights  
IP Due Diligence  
Intellectual Property Litigation  
Patents  
Trade Secrets  
Trademarks

### CONTACT

Aaron C. Dilbeck  
972-628-3694

### Education

Southern Methodist University  
Dedman School of Law  
Dallas, Texas 2016  
Juris Doctorate  
Honors: cum laude  
Executive editor, SMU Science and  
Technology Law Review  
AIPLA Giles Sutherland Rich Moot  
Court Competition—Best Advocate  
Team, 2016  
University of Illinois Urbana -  
Champaign  
Urbana, Illinois 2011  
B.S., Materials Science and

### Representative Experience

- Performed due diligence, conducted research, and drafted motions in lawsuits for patent infringement while representing a plaintiff or multiple defendants;
- Ensure protection of copyright and trademark rights.

### Presentations & Published Works

Article *Password-Sharing May Be a Federal Crime Under the Muddied Waters of the CFAA*, Corporate Counsel, January 5, 2018.

Supreme Court Participates in Patent Reform: Judicial Case Management,  
18 SMU Sci. & Tech. L. Rev. 3 (2015)

### Professional Associations & Memberships

American Bar Association

Dallas Bar Association

Engineering  
Honors: International Engineering  
Scholarship recipient

## **Bar Admissions**

Texas, 2016